

Amendments to the Specification:

IIFW SENT

IDC-B1,AMD

At page 9, the paragraph beginning line ¹⁰7 to line ¹¹8, is to be amended as follows:

The ink jet printhead chip 52 (see Fig. 6) includes a silicon wafer substrate 8015. 0.35
Micron 1 P4M 12 volt CMOS microprocessing circuitry is positioned on the silicon wafer
substrate 8015.

CH
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